

IN THE CLAIMS

1. (Currently amended) A digital micro-mirror device (DMD) package[[s]], comprising:
 - a base substrate having a top surface and a bottom surface;
 - a metallic layer ~~formed~~ adhesive disposed on the top surface of the base substrate;
 - ~~a metallic adhesive formed on the metallic layer;~~
 - a semiconductor chip ~~mounted on~~ overlying the metallic adhesive, ~~the base substrate~~ and electrically connected with the semiconductor chip base substrate;
 - a metallic layer disposed between the semiconductor chip the metallic adhesive;
 - one or more mirrors mounted on the semiconductor chip;
 - a hermetic sealing means covering the semiconductor chip including the one more mirrors.
2. (Original) The DMD package of claim 1, which further comprises a heat sink attached on the bottom surface of the base substrate.
3. (New) The DMD package of claim 1, wherein the base substrate is selected from the group consisting of a ceramic board, a plastic board, and a printed circuit board.
4. (New) The DMD package of claim 1, wherein the metallic layer is selected from the group consisting of Va, Au, Ni, Ag, Cu, Al, Pb, Sn, Sb, Pd, and metal-containing compounds thereof.
5. (New) The DMD package of claim 1, wherein the metallic adhesive is solder.